

### AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

#### Listing of Claims

1 (currently amended): A film carrier tape for mounting electronic part comprising an insulating film and a wiring pattern, which is made of a conductive metal and is provided on ~~the~~a surface of the insulating film, wherein:

an undercoating layer containing nickel as a main constituent is formed on at least a part of ~~the~~a surface of the wiring pattern made of a conductive metal, an intermediate layer containing palladium as a main constituent is formed on ~~the~~a surface of the undercoating layer, a surface layer containing gold as a main constituent is formed on ~~the~~a surface of the intermediate layer, and the average thickness of the intermediate layer containing palladium as a main constituent is not more than about 0.04  $\mu\text{m}$ .

2 (currently amended): The film carrier tape for mounting electronic part as claimed in claim 1, wherein the ratio of the average thickness of the intermediate layer containing palladium as a main constituent to the average thickness of the surface layer containing gold as a main constituent (palladium:gold) is in the range of about 1:2.5 to about 1:1000.

3 (currently amended): The film carrier tape for mounting electronic part as claimed in claim 1, wherein the ratio of the average thickness of the intermediate layer containing palladium as a main constituent to the average thickness of the undercoating layer containing nickel as a main constituent (palladium:nickel) is in the range of about 1:2.5 to about 1:2500.

4 (currently amended): The film carrier tape for mounting electronic part as claimed in claim 1, wherein the ratio of the average thickness of the surface layer containing gold as a main constituent to the average thickness of the undercoating layer containing nickel as a main constituent (gold:nickel) is in the range of about 1:0.05 to about 1:50.

5 (currently amended): The film carrier tape for mounting electronic part as claimed in claim 1, wherein ~~the~~a surface of the surface layer containing gold as a main constituent has a gold content of not less than about 93% by atom and has a nickel content of not more than about 5% by atom.

6 (currently amended): The film carrier tape for mounting electronic part as claimed in claim 1, wherein the surface of the surface layer containing gold as a main constituent has a copper content of not more than about 3% by atom.

7 (currently amended): The film carrier tape for mounting electronic part as claimed in claim 1, wherein the undercoating layer containing nickel as a main constituent, the intermediate layer containing palladium as a main constituent and the surface layer containing gold as a main constituent are formed at ~~the~~an inner terminal of the wiring pattern electrically connected to at least one of the electronic part ~~and/or the~~and an outer terminal of the film carrier.

8 (currently amended): The film carrier tape for mounting electronic part as claimed in claim 1, wherein the wiring pattern made of a conductive metal is formed from at least one of copper ~~or~~and a copper alloy.